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Structural study of refractory-metal-free C40 TiSi₂ and its transformation to C54 TiSi₂

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The structure of laser-induced refractory-metal-free C40 TiSi₂ has been studied by glancing-angle x-ray diffraction (GAXRD) in detail. The result shows that laser-induced C40 TiSi₂ has a hexagonal structure with the *P*6₂22 space group and lattice parameters *a*=0.467 nm and *c*=0.662 nm. The ordering effect and the stress effect on the TiSi₂ film are also discussed based on the GAXRD and micro-Raman results. The C40 phase completely transforms to the technologically important C54 phase at a relatively low temperature of 700 °C. © 2002 American Institute of Physics. [DOI: 10.1063/1.1466521]

The formation of C54 TiSi₂ has attracted a great deal of attention owing to its significant technological importance in the self-aligned silicide (salicide) processes in ultra-large-scale integration. In a typical salicide process in semiconductor device fabrication, a layer of silicide thin film is formed by reaction between the deposited metal Ti and Si surfaces on gate, source, and drain areas during rapid thermal processing (RTP). As is well known, C49 TiSi₂, a metastable phase of TiSi₂ with a high resistivity of 60–90 μΩ m is usually observed before the formation of C54 TiSi₂, which has low resistivity (~15 μΩ m) and high thermal stability.^{1–5} However, this C49–C54 TiSi₂ phase transformation becomes very difficult and incomplete for subquarter micron devices due to the lack of sufficient C49 TiSi₂ triple-grain boundaries where C54 TiSi₂ nucleate.^{5,6}

Recently, significant breakthroughs were reported in which the C54 phase was epitaxially formed from a metastable C40 phase bypassing the C49 phase. Mann *et al.*,⁷ and Kittl, Gribelyuk, and Samavedam⁸ observed that the C40 phase acts as a template allowing the direct formation of the C54 phase and blocking the formation of the C49 phase when a small amount of Mo ions were implanted into the Si substrate prior to Ti film deposition. Another method of forming C40 TiSi₂ is by depositing a thin Mo layer of 1 nm in thickness between the Ti film and Si substrate as demonstrated by Mouroux *et al.*⁹ However, as Chen *et al.*¹⁰ discussed, the use of refractory metals also raised several important issues. More recently, the refractory-metal-free C40 TiSi₂ was synthesized by Chen *et al.*,¹⁰ using a laser-annealing process and identified by Li, Chen, and Shen¹¹ using convergent beam electron diffraction (CBED) and CBED pattern simulation. In their work, the formation of C40 TiSi₂ was attributed to kinetic factors resulting from the extreme thermal nonequilibrium induced by the pulsed laser annealing.

As a new TiSi₂ phase, the crystal structure of C40 TiSi₂ has been systematically investigated by high-resolution transmission electron microscopy (HRTEM),¹¹ and the direct phase transformation from the C40 phase to C54 phase was studied by Raman spectroscopy.^{10,11} However, the pure C40–C54 transformation bypassing the C49 TiSi₂ phase has never been studied by x-ray diffraction (XRD), even the XRD pattern of the pure C40 phase resulting from the refractory-metal-free Ti/Si samples. In this work, we used x-ray diffraction to characterize C40 TiSi₂ directly formed by pulsed laser annealing a pure Ti/Si sample and the C40–C54 TiSi₂ phase transformation upon further RTP annealing.

The preparation of precursor Ti/Si samples and the pulsed laser annealing process has been reported in detail by Chen *et al.*¹⁰ and Li, Chen, and Shen.¹¹ A Digital Instruments (Dimension™ 3000 SPM) atomic-force microscope (AFM) with tapping mode was used to demonstrate the morphology and average grain size of pure C40 TiSi₂ induced by laser annealing. A RTP processor (Jipelec JetFirst system) was employed to transform pure C40 TiSi₂ to C54 TiSi₂ by heating the samples at different temperatures for 60 s. The samples after various temperature RTP treatments were identified by a SPEX 1702/04 micro-Raman spectrometer with a He–Ne laser (λ=632.8 nm) as the excitation source.

Figure 1(a) shows the typical top-view AFM image of the laser-irradiated sample after etching in NH₄OH:H₂O₂:H₂O=1:1:6 for complete removal of the unreacted surface Ti film. As shown, the average grain size is about 50 nm with a high uniformity of grain size and distribution.

Figure 1(b) (bottom spectrum) displays the Raman modes of the same as-laser-annealed sample. Compared with the previous results,^{10,11} it is obvious that pure C40 TiSi₂ is the dominant phase after the laser annealing process in this work.

The crystal structure of C40 TiSi₂ has been identified using HRTEM by Li, Chen, and Shen¹¹ and normal Bragg–Bentano XRD by Via *et al.*¹² By using glancing-angle XRD

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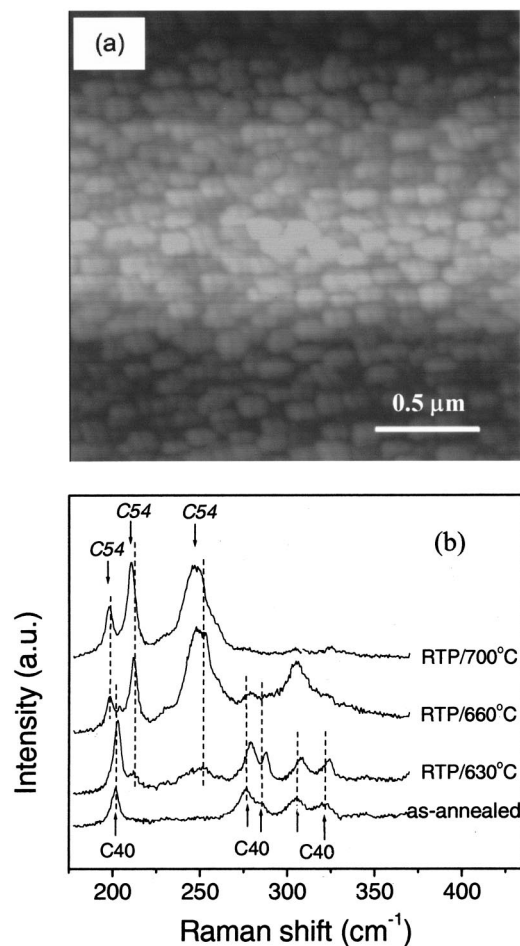


FIG. 1. (a) AFM image of the TiSi_2 C40 phase produced by laser anneal of the Ti/Si sample. (b) Raman spectra of the C40 phase before and after RTP treatments.

(GAXRD) operating under the detector scan mode to analyze the samples instead of the common Bragg–Bentano XRD (BBXRD) method, which operates at the θ – 2θ mode, we can effectively multiply the x-ray diffraction by the surface TiSi_2 thin film and strongly reduce the penetration depth and collection time.¹³ The crystal structure of the refractory-metal-free C40 TiSi_2 and C40–C54 phase transformations were studied by GAXRD at room temperature. In this work, XRD patterns were taken using a D8 ADVANCE x-ray diffractometer (Bruker Analytical X-Ray Systems). A $\text{Cu } K\alpha_1$ x-ray source ($\lambda=1.5406 \text{ \AA}$) was used at 40 kV and 40 mA. The GAXRD diffraction geometry is shown schematically in Fig. 2(a). The incidence angle α was fixed at 2° relative to the sample surface while the detector was rotated to collect the diffracted x-ray during the scan. As shown in Fig. 2(b) (bottom curve), the GAXRD pattern of pure C40 TiSi_2 presents five peaks at 37.96° , 40.43° , 41.04° , 43.92° , and 47.24° . For comparison, the XRD peak positions for the $\text{Ti}_{0.4}\text{Mo}_{0.6}\text{Si}_2$ (Ref. 14a) ($a=0.465 \text{ nm}$, $c=0.650 \text{ nm}$), $\text{Ti}_{0.8}\text{Mo}_{0.2}\text{Si}_2$ (Ref. 14b) ($a=0.470 \text{ nm}$, $c=0.652 \text{ nm}$), and TaSi_2 (Ref. 14c) ($a=0.478 \text{ nm}$, $c=0.657 \text{ nm}$) were also indicated in Fig. 2(b). It is obvious that the XRD peaks of laser-induced refractory-metal-free C40 TiSi_2 match well with the other well-known C40 phase silicides, all of which have the hexagonal crystal structure with space group $P6_222$ (180). Especially, the peak positions of laser-induced C40 TiSi_2 are quite close to that of

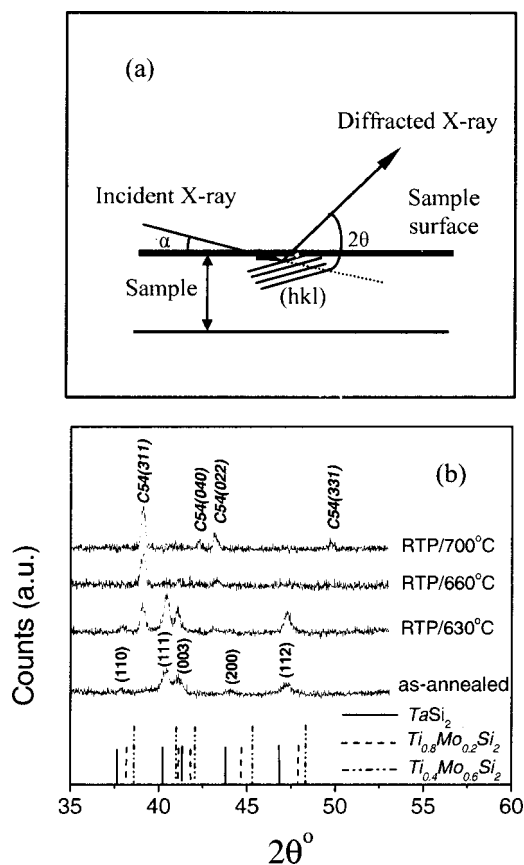


FIG. 2. (a) Schematic diagram of the GAXRD geometry, incidence angle α of the x ray is fixed at 2° and the detector is scanned during experiment. (b) XRD patterns of the as-laser-annealed C40 TiSi_2 sample before and after RTP treatments.

TaSi_2 . This can be explained as the small difference in lattice parameters between C40 TiSi_2 and TaSi_2 as reported by Via *et al.*¹² It is noted that the results of Li, Chen, and Shen¹¹ have shown that pure C40 TiSi_2 has a hexagonal structure ($P6_222$). Therefore, we set the XRD pattern shown in Fig. 2(b) (bottom) as the hexagonal structure with space group $P6_222$. After addressing the five peaks to the (110), (111), (003), (200), and (112) planes of C40 TiSi_2 , we obtained the experimental lattice parameters ($a=0.467 \text{ nm}$, $c=0.662 \text{ nm}$) of pure C40 TiSi_2 . It is well matched with the HRTEM results ($a=0.471 \text{ nm}$, $c=0.653 \text{ nm}$),¹¹ and BBXRD results ($a=0.469 \text{ nm}$, $c=0.649 \text{ nm}$).¹² Our experimental results for the interplanar distance, 2.19 \AA for the (003) plane, 2.23 \AA for the (111) plane, and 1.92 \AA for the (112) plane, also show excellent agreement with the HRTEM results of 2.18 , 2.21 , and 1.92 \AA , respectively.¹¹

In order to study the phase transformation from C40 TiSi_2 to C54 TiSi_2 , we used RTP to anneal the laser-induced C40 TiSi_2 sample at various temperatures for the same duration (60 s). Figure 2(b) illustrates the GAXRD patterns of C40 TiSi_2 after annealing at different temperatures. As shown, the C54 phase appears after a relative low-temperature ($T=630^\circ\text{C}$) RTP treatment. Interestingly, the peak intensity of XRD peaks belonging to C40 TiSi_2 increases dramatically with a large reduction of the full width at half maximum (FWHM), even after the appearance of the C54 phase. By considering the typical x-ray diffraction theory, it is quite reasonable to attribute this phenomenon to

the ordering and perfecting process of crystalline C40 TiSi₂ caused by low-temperature RTP annealing. Notice that the coexistence of the more-ordered C40 phase, and the C54 phase is strongly related to the epitaxial growth behavior between C40 TiSi₂ and C54 TiSi₂. With the increase in temperature, the dominant phase transforms from the C40 TiSi₂ before RTP to the C54 TiSi₂ after RTP at 660 °C for 60 s. Further annealing ($T=700$ °C) completely transforms C40 TiSi₂ to C54 TiSi₂, characterized by the XRD pattern of the pure C54 TiSi₂ phase.¹⁵ Our XRD results indicate that C49 TiSi₂ is never formed for all RTP treated ($T=625$ – 700 °C) laser-induced C40 TiSi₂ samples. Hence, the laser-induced refractory-metal-free C40 TiSi₂ can greatly decrease the C54 TiSi₂ formation temperature and directly transform to the C54 phase, completely bypassing the C49 TiSi₂.

Figure 1(b) also shows the Raman spectra of the samples corresponding to the GAXRD patterns shown in Fig. 2(b), which strongly support the conclusions drawn from the XRD study that the laser-induced refractory-metal-free C40 TiSi₂ can directly transform to C54 TiSi₂, bypassing the C49 phase. A detailed Raman study has been presented by Chen *et al.*¹⁰ that demonstrated the same result. Similar to the XRD peaks, the Raman peaks of the C40 phase also display a dramatic increase of intensity and decrease of FWHM. Peak splitting at around 280 cm⁻¹ is clearly seen in the 630 °C annealed spectrum, corresponding to a more-ordered C40 TiSi₂ phase. More interestingly, an obvious blueshift of the C40 TiSi₂ vibrational modes occurs with increasing RTP temperature while a slight redshift of the C54 TiSi₂ vibrational modes can be observed with further annealing. The Raman mode shifts most likely result from stress, which is mainly caused by the mismatch between the substrate Si and the C40 TiSi₂ as well as between C40 and C54 TiSi₂. Raman

modes are very sensitive to stress, and different kinds of stress (compress or tensile) induce contrast shifts (blueshift or redshift)¹⁶ in the Raman spectra.

In conclusion, the structure of laser-induced refractory-metal-free C40 TiSi₂ has been studied using GAXRD. Both GAXRD and the Raman study unambiguously demonstrate that this laser-induced C40 TiSi₂ can directly transform to C54 TiSi₂, bypassing C49 TiSi₂ at a relatively low temperature.

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